

Title (en)

INDUCTIVE COMPONENT AND METHOD FOR MANUFACTURING AN INDUCTIVE COMPONENT

Title (de)

INDUKTIVES BAUELEMENT UND VERFAHREN ZUM HERSTELLEN EINES INDUKTIVEN BAUELEMENTS

Title (fr)

COMPOSANT INDUCTIF ET PROCEDE DE REALISATION D'UN COMPOSANT INDUCTIF

Publication

EP 2018643 A1 20090128 (DE)

Application

EP 07728738 A 20070503

Priority

- EP 2007054285 W 20070503
- DE 102006022785 A 20060516

Abstract (en)

[origin: WO2007131884A1] The invention relates to a method for manufacturing an inductive component that is constructed from multiple layers in which the following steps are performed: a) Arrangement of an electrically conducting material (511 to 514; 521 to 524) as a winding of the component (I, II, III, IV) on a first nonmagnetic dielectric ceramic layer (5; 5a to 5h); b) Construction of at least one continuous recess (53, 53', 53", 53''') in the nonmagnetic dielectric ceramic layer (5, 5a to 5h); c) Arrangement of a first magnetic ceramic layer (6) on an upper side and of a second magnetic ceramic layer (7) on an underside of the nonmagnetic dielectric ceramic layer (5, 5a to 5h); and d) Performing a process step in which at least one of the magnetic ceramic layers (6, 7) is plastically deformed, in such a way that both the magnetic ceramic layers (6, 7) are contacted in the region of the recess (53, 53', 53", 53''') and form a magnetic core of the component (I, II, III, IV). The invention also relates to an inductive element of this type.

IPC 8 full level

H01F 41/02 (2006.01)

CPC (source: EP KR US)

H01F 17/0013 (2013.01 - EP US); **H01F 17/043** (2013.01 - EP US); **H01F 27/2804** (2013.01 - EP US); **H01F 41/02** (2013.01 - KR); **H01F 41/0233** (2013.01 - EP US); **H01F 41/041** (2013.01 - EP US); **H01F 1/344** (2013.01 - EP US); **H01F 1/348** (2013.01 - EP US); **Y10T 29/49073** (2015.01 - EP US)

Citation (search report)

See references of WO 2007131884A1

Designated contracting state (EPC)

DE FR GB HU IT

Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

DE 102006022785 A1 20071122; CN 101443863 A 20090527; CN 101443863 B 20120530; DE 502007005763 D1 20110105; EP 2018643 A1 20090128; EP 2018643 B1 20101124; JP 2009537976 A 20091029; JP 4971432 B2 20120711; KR 101433838 B1 20140827; KR 20090015975 A 20090212; TW 200802436 A 20080101; US 2009102591 A1 20090423; US 7973631 B2 20110705; WO 2007131884 A1 20071122

DOCDB simple family (application)

DE 102006022785 A 20060516; CN 200780017706 A 20070503; DE 502007005763 T 20070503; EP 07728738 A 20070503; EP 2007054285 W 20070503; JP 2009510399 A 20070503; KR 20087030628 A 20070503; TW 96116383 A 20070509; US 30090907 A 20070503